Current Production Information				1				
TI Part Number		PGA2311U/1KG4		Assembly Site		TI TAIWAN A/T		
Lead/Ball Finish		CU NIPDAU		Package Type / Pins		DW 16		
Planned Lead/Ball Finish				Package Body Size (WxLxH) mm		7.52x10.28x2.35		
MSL / Reflow Ratings		Level-2-260C-1 YEAR		Total Device Mass (mg)		420.37374300000005		
Environmental Ratings Informat	tion							
Part Number Type		Pb-Free		JIG Material Content Compliance		Level A & B		
RoHS & High-Temp Compliant		Υ		Green Compliant		Υ		
Pb-Free (RoHS) Conversion Date		01-Apr-2006 (DC 0614)		Green Conversion Date		01-Apr-2006 (DC 0614)		
Pb-Free (RoHS) Available Supply Date		06-Nov-2006		Green Available Supply Date		06-Nov-2006		
Component Information								
				Homogeneous Material	Level	Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm	
Bond Wire						<u> </u>		
Metallurgy	Gold	7440-57-5	0.199975	99.9925	999924	0.0476	475	
Trace Metal	Beryllium	7440-41-7	0.000002	0.001	10		0	
Trace Metal	Calcium	7440-70-2	0.000002	0.001	10		0	
Trace Metal	Indium	7440-74-6	0.000006	0.003	30	_	0	
Trace Metal	Silver	7440-22-4	0.000005	0.0025	25	0	0	
Sub-Total			0.19999			0.0476	475	
Die Attach Adhesive								
Conductive Material	Silver	7440-22-4	0.21	70	699999	0.05	499	
Polymer	Epoxy	7110 22 1	0.039			0.0093	92	
Polymer	Proprietary Resin		0.0165	5.5		0.0039	39	
Reactive Diluent	Proprietary Material		0.0345	11.5	115000	0.0082	82	
Sub-Total	Troprietary Material		0.3			0.0714	712	
Lead Frame		•	0.0	,	100000	0.0714	,	
Base Metal	Copper	7440-50-8	105.914617	97.425	974250	25.1953	251953	
Base Metal	Iron	7439-89-6	2.609136	2.4	23999	0.6207	6206	
Base Metal	Lead	7439-92-1	0.032614		299	0.0078	77	
Base Metal	Phosphorus	7723-14-0	0.016307	0.015		0.0079	38	
Base Metal	Tin	7440-31-5	0.032614	0.03		0.0037	77	
Base Metal	Zinc	7440-66-6	0.108714	0.00	999	0.0259	258	
Sub-Total	Ziric	7440-00-0	108.714002			25.8613	258609	
Lead Frame Plating								
Plating	Gold	7440-57-5	0.000671	0.7802	7802	0.0002	1	
Plating	Nickel	7440-02-0	0.081803	95.1198		0.0002	194	
Plating	Palladium	7440-02-0	0.003526	4.1	41000	0.0008	Ω	
Sub-Total	i diladidiri	7440-03-3	0.003320			0.0205	203	
Mold Compound			0.080	100	1000000	0.0203	203	
Colorina	Carbon Black	1333-86-4	0.920321	0.3	2999	0.2189	2189	
Filler	Fused Silica	60676-86-0	233.148052	2 76		55.4621	554620	
Flame Retardant Additive	Proprietary Non Halide	00070-00-0	10.737081	3.5		2.5542	25541	
Hardener	Phenolic Novolac	+	23.008031	7.5		5.4732	54732	
Other additives	Catalyst Mold Release Adhesion Agent		11.350629			2.7001	27001	
Polymer	Cresol Novolac Epoxy		23.008031	7.5		5.4732	54732	
Stress Relief Agent	Proprietary		4.601606		14999	1.0946	10946	
Sub-Total	i roprictal y		306.773751			72.9764	729761	
Semiconductor Device			300.773751	100	1000000	72.7704	727701	
Silicon Chip	Doped Silicon	7440-21-3	4.3	100	1000000	1.0229	10228	
Sub-Total	Doped Silicon	1440-21-3	4.3			1.0229	10228	
		1			1000000			
Total			420.373743	i e		100	1000000	

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, SeeProduct Content Methodology,

Material Declaration Certificate for Semiconductor Products

TI certifies that the material content information provided by TI as of the date of disclosure is representative and accurate. TI semiconductor products designated by TI as "Pb-Free" or "Green" (defined below) do not exceed any of the Joint Industry Guide (JIG) Level-A Substance thresholds and are compliant with the requirements of the European Union's Restriction on Use of Hazardous Substances ("RoHS") Directive, 2002/95/EC.

For TI semiconductor products NOT designated as "Pb-Free" or "Green", these products are RoHS compliant with the exception of Lead (Pb) which may be found in the leadframe plating or solder balls, or in RoHS exempt applications such as high-temperature solder die attach (exemption 7a) and flip-chip solder bumps (exemption 15). This situation is known as RoHS-5 or "5 of 6" compliant.

JIG Level-A Banned Substances	Threshold, Homogeneous Level (1)			
Asbestos	Not intentionally added			
Azo colorants	Not intentionally added			
	75 ppm, Not intentionally added			
RoHS - Cadmium/Cadmium Compounds	(RoHS threshold = 100ppm)			
RoHS - Hexavalent Chromium/Hex.Chromium.Compounds	1000 ppm, Not intentionally added			
RoHS - Lead/Lead Compounds	1000 ppm, Not intentionally added			
RoHS - Mercury/Mercury Compounds	1000 ppm, Not intentionally added			
	Class I: Not intentionally added			
Ozone Depleting Substances	Class II: 1000ppm			
RoHS - Polybrominated Biphenyls (PBBs)	1000 ppm, Not intentionally added			
RoHS - Polybrominated Diphenyl Ethers (PBDEs)	1000 ppm, Not intentionally added			
Polychlorinated Biphenyls (PCBs)	1000 ppm, Not intentionally added			
Polychlorinated Naphthalenes (>3 Chlorine atoms)	1000 ppm, Not intentionally added			
Radioactive Substances	1000 ppm, Not intentionally added			
Shortchain Chlorinated Paraffins	1000 ppm, Not intentionally added			
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	1000 ppm, Not intentionally added			
Tributyl Tin Oxide (TBTO)	1000 ppm, Not intentionally added			
(1) Threshold does not apply to applications covered by a RoHS substance exemption.				

Regarding the EU Directive 2004/12/EC concerning Packaging and Packaging Waste, TI's packing materials (boxes, trays, etc) comply with the directive's requirement that the total concentration of the 4 heavy metals (cadmium, hexavalent chromium, lead, and mercury) must not exceed 100 ppm. Material content details for TI's packing materials are available at www.ti.com/ecoinfo.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at http://www.ti.com/sc/docs/stdterms.htm) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

Signature: (click here for signed certificate)

Name/Title: Cindy Allen, Vice President, Worldwide Quality

Date: September 27, 2006

Pb-Free: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes.

Green: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material).